

# HVB187YP

## Silicon Epitaxial Planar Pin Diode for High Frequency Attenuator

REJ03G0439-0100

(Previous: ADE-208-1411)

Rev.1.00 Dec 16, 2004

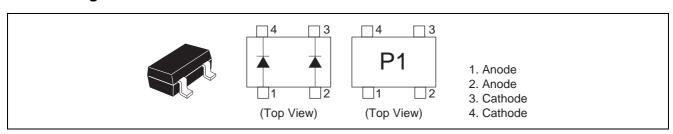
### **Features**

- Low forward resistance. (rf =  $5.5 \Omega$  max)
- CMPAK-4 package is suitable for high density surface mounting and high speed assembly.

## **Ordering Information**

Type No.	Laser Mark	Package Code
HVB187YP	P1	CMPAK-4

### **Pin Arrangement**



## **Absolute Maximum Ratings**

 $(Ta = 25^{\circ}C)$ 

Item	Symbol	Value	Unit
Reverse voltage	V <sub>R</sub>	60	V
Forward current	l <sub>F</sub>	50	mA
Power dissipation	Pd *1	100	mW
Junction temperature	Tj	125	°C
Storage temperature	Tstg	−55 to +125	°C

Note: 1. Per one device.

### **Electrical Characteristics**

 $(Ta = 25^{\circ}C)$ 

Item	Symbol	Min	Тур	Max	Unit	Test Condition
Reverse current	I <sub>R</sub>	_	_	100	nA	V <sub>R</sub> = 60 V
Forward voltage	V <sub>F</sub>	_	_	1.0	V	I <sub>F</sub> = 10 mA
Capacitance	С	_	_	2.4	pF	V <sub>R</sub> = 0 V, f = 1 MHz
Forward resistance	r <sub>f</sub>	3. 5	_	5.5	Ω	I <sub>F</sub> = 10 mA, f = 100 MHz
ESD-Capability *1	_	200	_	_	V	C = 200 pF, R = 0 $\Omega$ , Both forward
						and reverse direction 1 pulse.

Note: 1. Failure criterion;  $I_R > 100$  nA at  $V_R = 60$  V

### **Main Characteristic**

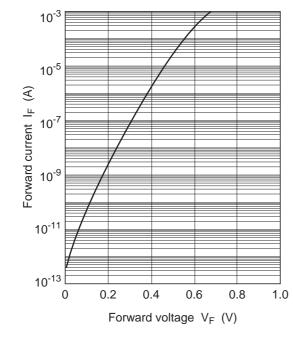


Fig.1 Forward current vs. Forward voltage

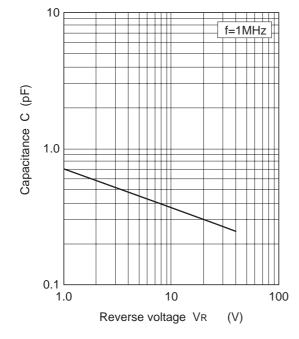


Fig.3 Capacitance vs. Reverse voltage

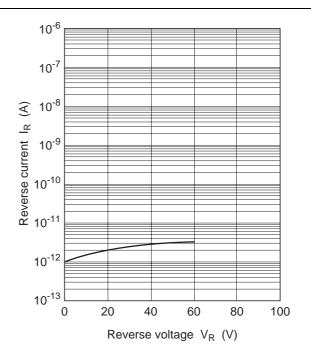


Fig.2 Reverse current vs. Reverse voltage

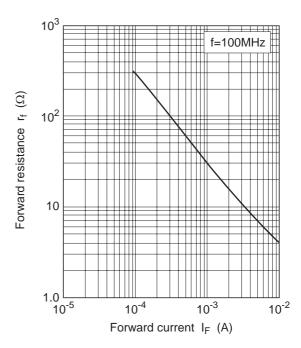
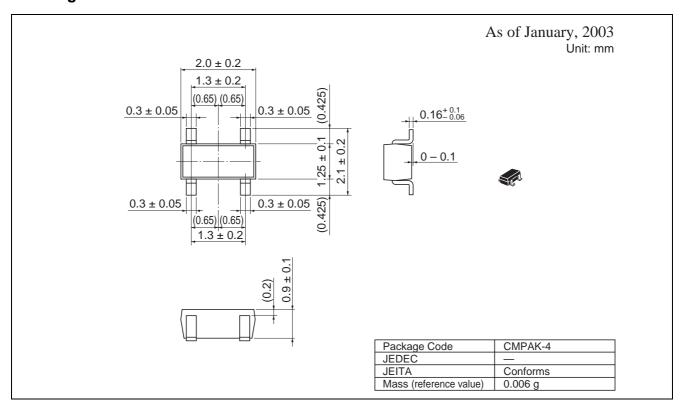


Fig.4 Forward resistance vs. Forward current

## **Package Dimensions**



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